

TN2010T-T1-E3-VB Datasheet

N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY

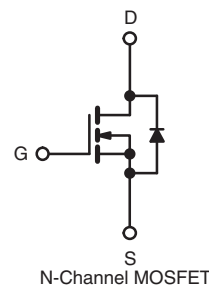
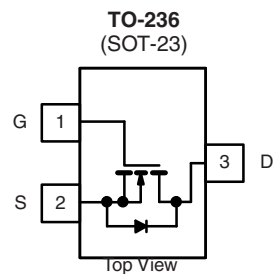
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
200	1.4 at $V_{GS} = 10$ V	0.6

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- 100 % R_g and UIS Tested
- Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE
Available



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	5 s	Steady State	Unit
Drain-Source Voltage	V_{DS}	200		V
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	0.6	0.45	A
		0.5	0.35	
Pulsed Drain Current ^b	I_{DM}	2.5		
Avalanche Current ^b	I_{AS}	2.5		mJ
Single Avalanche Energy	E_{AS}	50		
Continuous Source Current (Diode Conduction) ^a	I_S	0.6		A
Power Dissipation ^a	P_D	1.55	1.03	W
		1.20	0.87	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	80	100	$^\circ\text{C/W}$
		130	170	
Maximum Junction-to-Foot	R_{thJF}	45	55	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.

SPECIFICATIONS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

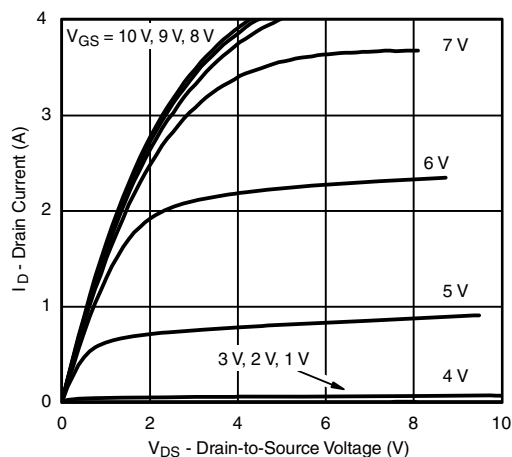
Parameter	Symbol	Test Conditions	Limits			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 1 mA	200			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.5		4.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	μA
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 70 °C			75	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 15 V, V _{GS} = 10 V	2.5			A
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 0.5 A		1.4		Ω
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 0.5 A		4		S
Diode Forward Voltage	V _{SD}	I _S = 1 A, V _{GS} = 0 V		0.8	1.2	V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 0.5 A		3	5	nC
Gate-Source Charge	Q _{gs}			0.37		
Gate-Drain Charge	Q _{gd}			1.45		
Gate Resistance	R _g		0.5	1.3	2.4	Ω
Switching						
Turn-On Delay Time	t _{d(on)}	V _{DD} = 100 V, R _L = 33 Ω I _D ≅ 0.2 A, V _{GEN} = 10 V, R _g = 6 Ω		7	11	ns
Rise Time	t _r			10	15	
Turn-Off Delay Time	t _{d(off)}			9	15	
Fall Time	t _f			11	15	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 0.5 A, dI/dt = 100 A/μs50100				

Notes:

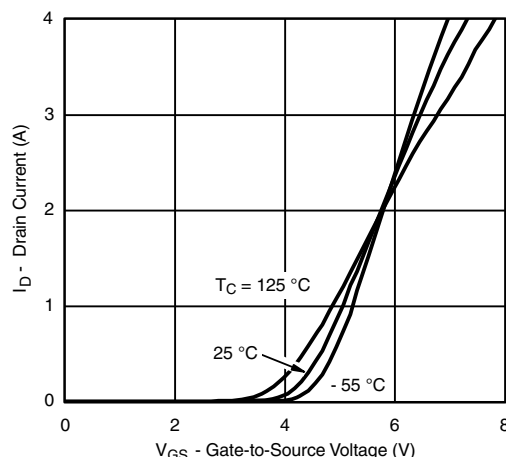
a. Pulse test: $PW \leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

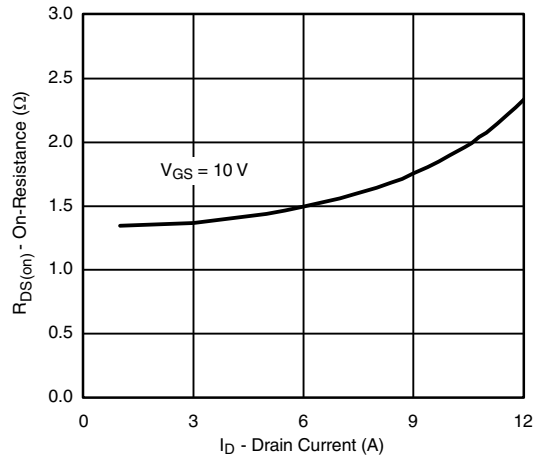
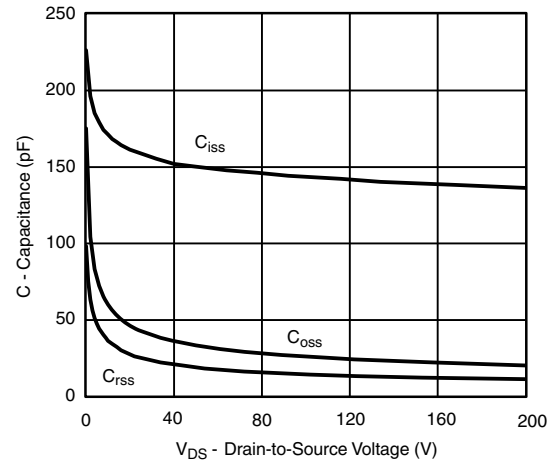
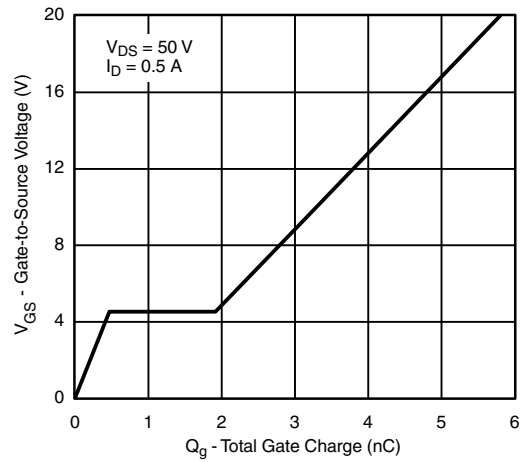
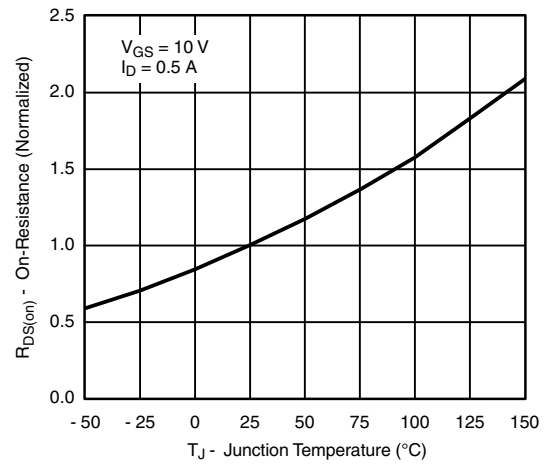
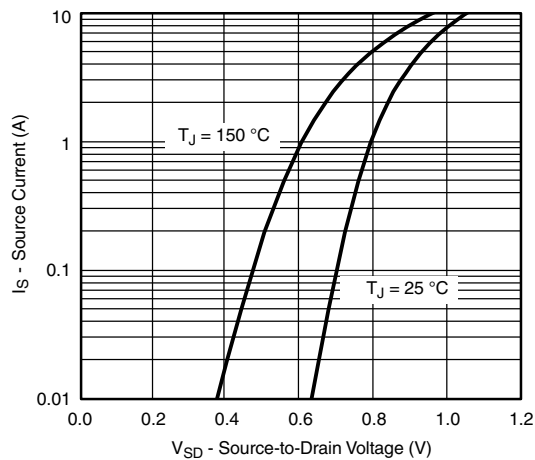
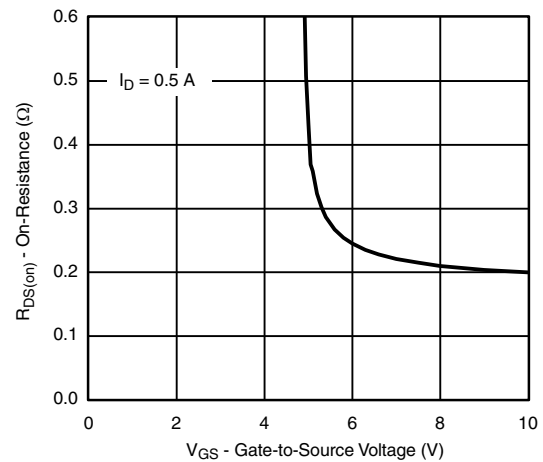
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25°C , unless otherwise noted)

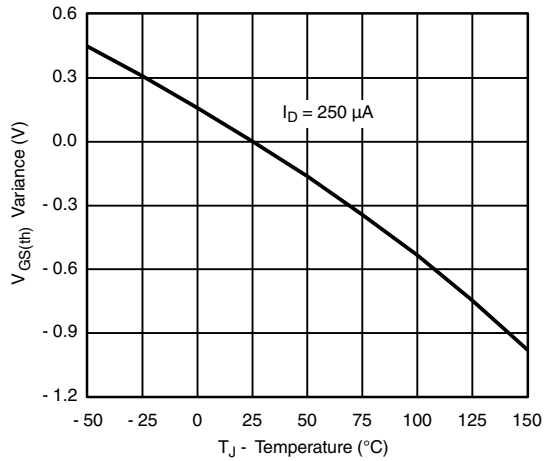
Output Characteristics



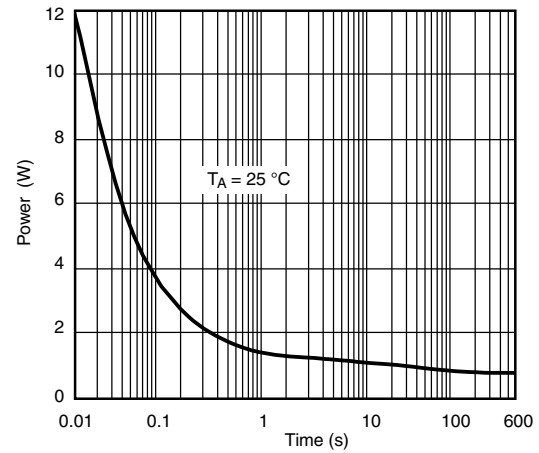
Transfer Characteristics

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

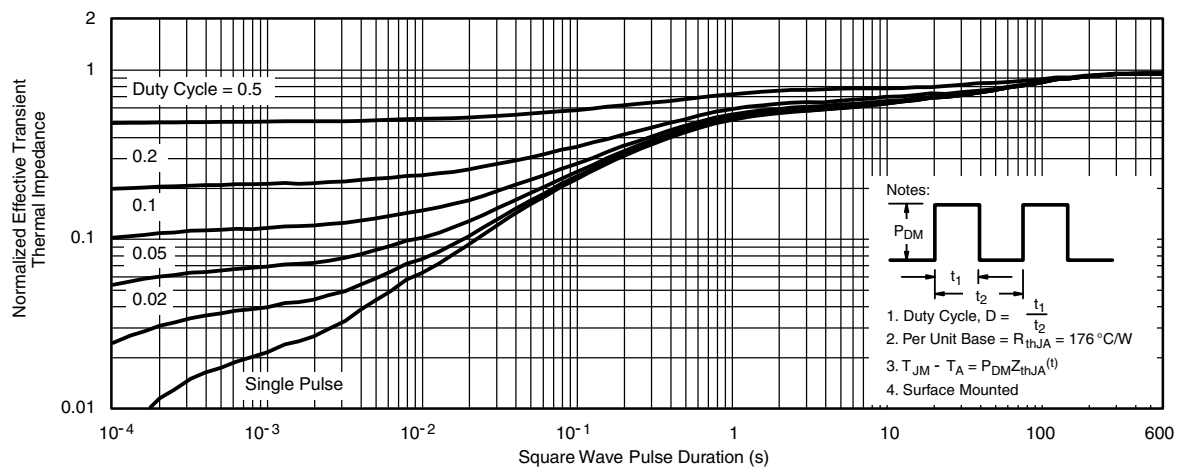
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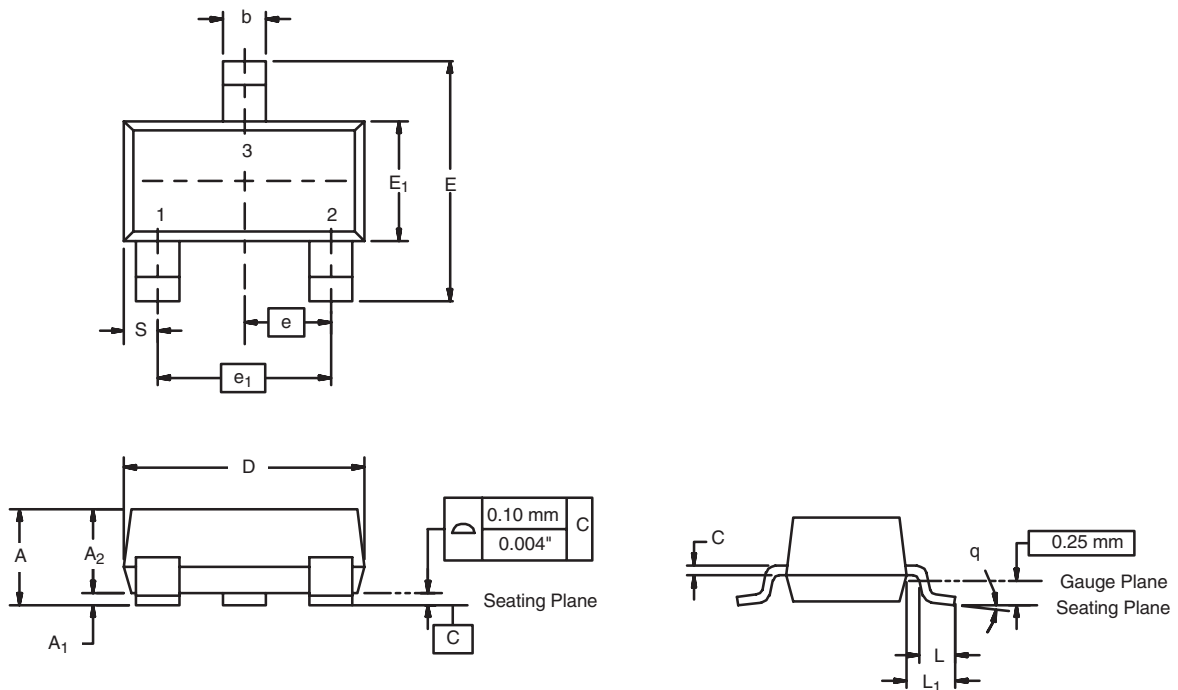
Threshold Voltage



Single Pulse Power

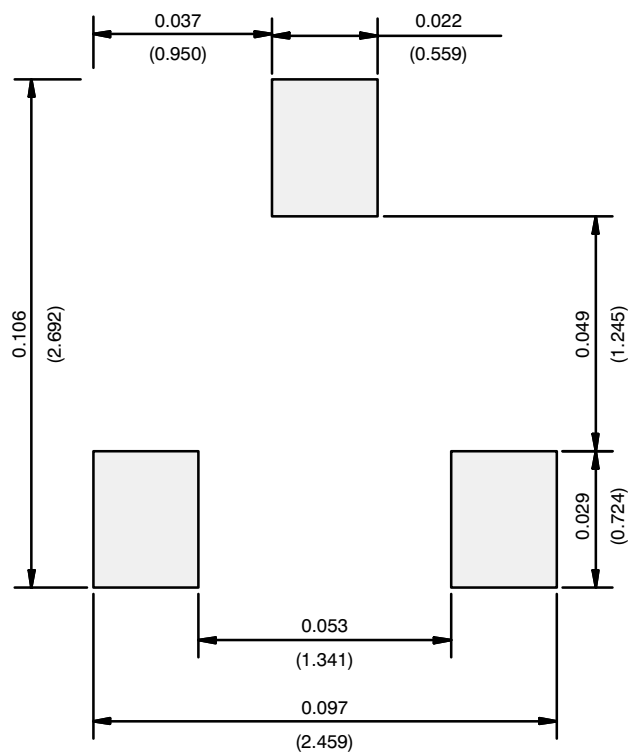


Normalized Thermal Transient Impedance, Junction-to-Ambient

SOT-23 (TO-236): 3-LEAD

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°
ECN: S-03946-Rev. K, 09-Jul-01 DWG: 5479				

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

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